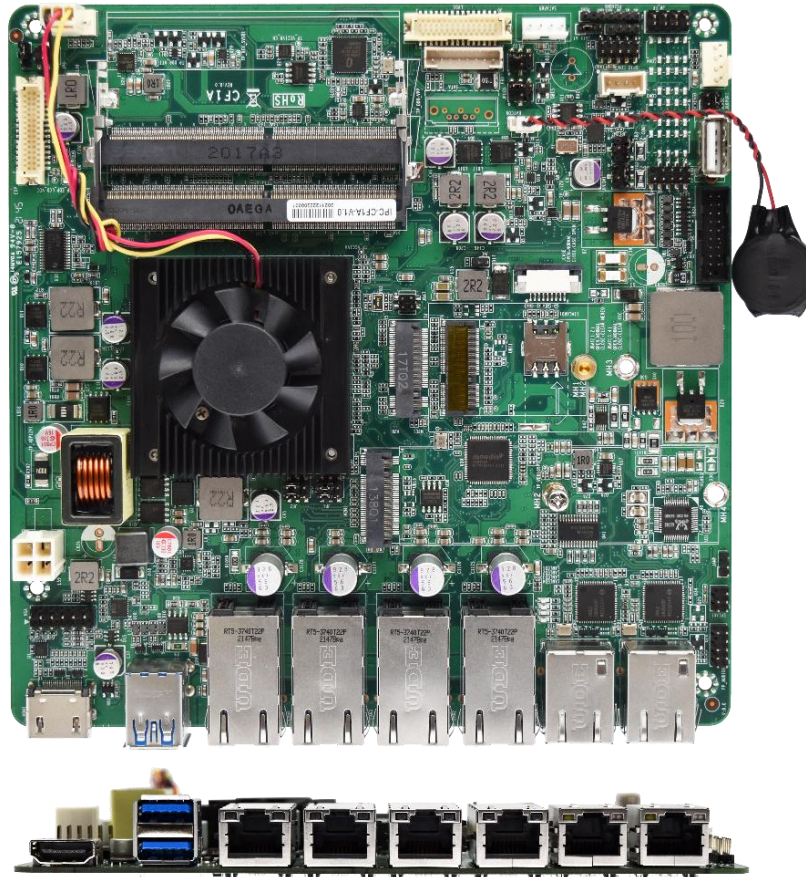


IPC-TGL6L Embedded Motherboard



Features

- Low power consumption TDP 15W(i5-1135G7), Intel Core 11th Gen U-series, Petium/Celeron/Atom platform
- Wide power supply
- Support PoE power supply
- Support CAN OPEN
- Support 2 RS485
- Support 16BIT GPIO
- Support I2C direct screen connection
- Dual channel memory slot

Application

4 PoE can be directly linked to industrial cameras applications in the field of machine vision, serial port and USB port can simultaneously support peripheral applications, CAN port can support motion control.

6 NICs can be applied to gateway, net gap applications.



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Support LVDS +EDP+I2C, can directly drive the screen, special USB TP interface is applicable to industrial panel PC.

Advantage

- 1. Long Time Product Support.** Fodenn uses selected industrial use material, provides as long as 15 years product support, maintain our product stability and customer loyalty.
- 2. Rich I/O port.** All Fodenn industrial motherboard support multiple I/O port, from 8* PCIE 16X to 18*USB, 14*COM, 6*RJ45, 4*PoE, CAN-OPEN, etc. Customer can easily find out our standard product that meet their requirement.
- 3. Easy upgrade.** Industrial motherboards designed by Fodenn provide standard layout from H81 to H610 chipset, and will continue to provide convenience when our customer need upgrade.

Specifications

CPU/CHIP	Onboard Intel Tiger Lake i5-1135G7 CPU, support Intel Core 11th Gen U-series, Petium/Celeron/Atom platform AMI 128Mbit SPI FLASH
Power	12-36V DC in
DRAM	2*SO-DIMM For DDR4 2400MHz Max 64GB
SSD	1*M.2 Socket (2242/2280, SATA/NVMe, Jumper, Default NVMe) 1*SATAIII
DISPLAY	1*HDMI2.0b: 4096*2304@60Hz (EXT) 1*CRT: 2560*1600@60Hz (Hi-EXT, Option) 1*EDP: 4096*2304@60Hz (INT) 1*LVDS: 2560*1600@60Hz
LAN	10/100/1000 Mbps 4*Intel I211AT (PoE PS) + 2*Intel I211AT GIGALAN
Audio	Front_FP (Support ALC888S/ALC897/ALC662) + 3W Speaker
Front I/O	1*HDMI 2*USB3.1 6*RJ45(4*PoE, ASM1806 FOR 4*LAN, 2*Intel PCI-E)
Internal Connectors	1* DC Connector (4PIN Power connector) 1* M.2 (M key 2242/2280 for SSD, SATA/NVMe, Jumper, Default NVMe) 1* M.2 (B key 3042/3052 for 4G/5G) 1* M.2 (E key 2230 PCI-E,USB2.0) 1*CRT (15pin Header, Option) 1* USB3.0 2* USB2.0 +1*USB2.0(For TP) +1*USB2.0 4* COM (COM1/COM2: RS232/422/485, COM3~4: RS232)



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	1* CAN (F81251) 1* SATAIII+1*SATA Power 1* 16bit GPIO (5V) 1* SIM Card hold(Co-lay FPC Connector) 1* CPU FAN (Support smart FAN) 1* SYSTEM FAN (W/O Smart FAN) 1* AT_Mode 1* FP_PW (PS ON)
Other	Support SMBus/I2C
Temperature Range	Operation: -10~60°C Non-Operation: -20~70°C
Dimensions	PCB SIZE: 170*170mm(ITX)